Dual P-Channel 30V (D-S) MOSFET

Product Summary		
V_{DS}(V)	$R_{DS(on)}$ (mΩ) (Max.)	I_D (A)
-30	5.5 at V_{GS} = -10 V	-60
	7.8 at V_{GS} = - 4.5 V	-60

Features

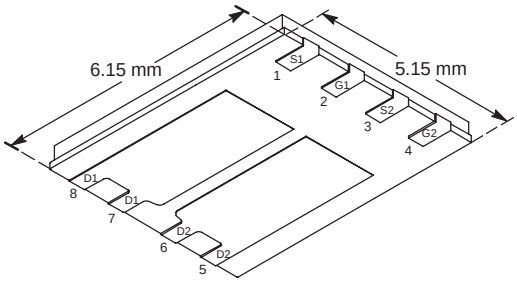
- Very Low RDS(on) at 4.5V Vgs
- Low Gate Charge
- High Current Capability
- 100% Rg and UIS Tested
- RoHS and Halogen-Free Compliant

APPLICATIONS

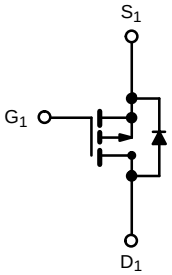
- Battery and Load Switching for Notebook PCs

Pin Configuration

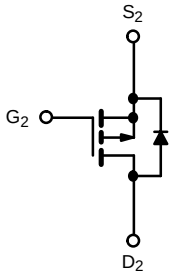
Power5x6



Bottom View



P-Channel MOSFET



P-Channel MOSFET

Absolute Maximum Ratings

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	-30	V
Gate-Source Voltage		V_{GS}	±20	V
Continuous Drain Current[G]	T_C=25℃	I_D	-60	A
	T_C=70°C		-60	
Pulsed Drain Current [C]		I_{DM}	-100	
Continuous Drain Current	T_A=25℃	I_{DSM}	-20.8	A
	T_A=70℃		-16.6	
Avalanche Current [C]	L = 0.1 mH	I_{AS},	-30	
Avalanche E nergy		E_{AS}	45	mJ
Power Dissipation [B]	T_C=25℃	P_D	46	W
	T_C=70°C		29	
Power Dissipation [A]	T_A=25℃	P_{DSM}	3.5	W
	T_A=70℃		2.2	
Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	℃

Thermal Data

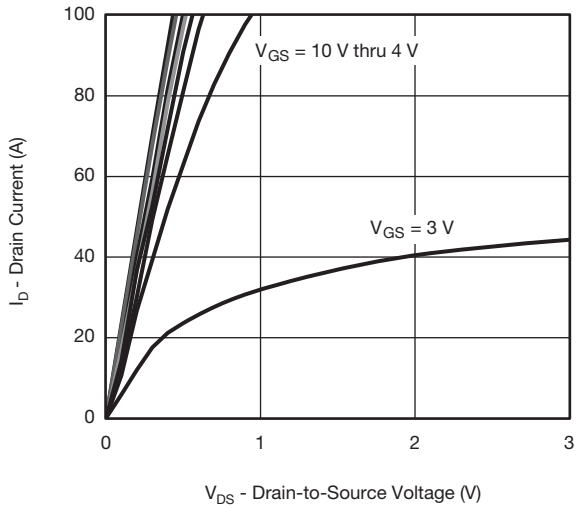
Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient [A]	t ≤ 10s	$R_{\theta JA}$	26	35	℃/W
Maximum Junction-to-Case	Steady-State	$R_{\theta JC}$	2.2	2.7	℃/W

Electrical Characteristics (T_J =25℃ Unless Otherwise Specified)

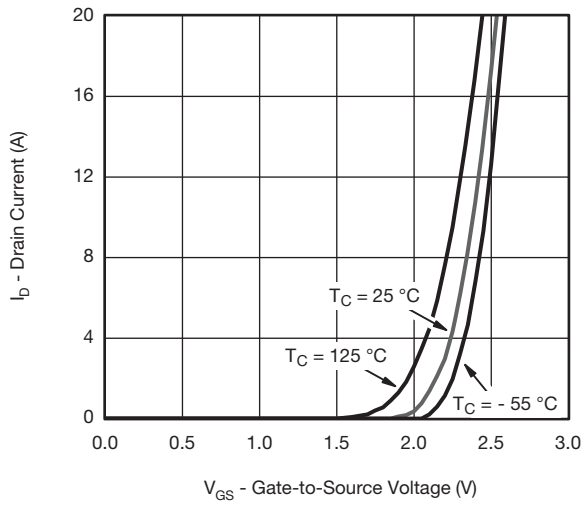
Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	I_D=-250μA, V_{GS}=0V	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=-30V, V_{GS}=0V			-1	μA
		T_J=55°C			-10	
I_{GSS}	Gate-Body leakage current	V_{DS}=0V, V_{GS}= ±20V			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS} I_D=-250μA	-1.0		-2.2	V
$I_{D(ON)}$	On state drain current	V_{GS}=-10V, V_{DS} ≤ -5V	-20			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	V_{GS}=-10V, I_D=-20A		4.5	5.5	mΩ
		V_{GS}=-4.5V, I_D=-20A		6.3	7.8	mΩ
g_{FS}	Forward Transconductance	V_{DS}=-15V, I_D=-20A		71		S
V_{SD}	Diode Forward Voltage	I_S=-10A,V_{GS}=0V		-0.8	-1.2	V
I_S	Maximum Body-Diode Continuous Current[G]				-38	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{GS}=0V, V_{DS}=-15V, f=1MHz		6200		pF
C_{oss}	Output Capacitance			615		pF
C_{rss}	Reverse Transfer Capacitance			560		pF
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, f=1MHz	0.9	4.6	9.2	Ω
SWITCHING PARAMETERS						
Q_g(10V)	Total Gate Charge	V_{GS}=-10V, V_{DS}=-15V, I_D=-20A		106	160	nC
Q_g(4.5V)	Total Gate Charge	V_{GS}=-4.5V, V_{DS}=-15V, I_D=-20A		51	77	nC
Q_{gs}	Gate Source Charge			17		nC
Q_{gd}	Gate Drain Charge			16.5		nC
$t_{D(on)}$	Turn-On DelayTime	V_{DD}=-15V, R_L=1.5 Ω, I_D ≅-10A,V_{GEN} =4.5V, R_g =1Ω		60	90	ns
t_r	Turn-On Rise Time			50	75	ns
$t_{D(off)}$	Turn-Off DelayTime			80	120	ns
t_f	Turn-Off Fall Time			40	60	ns
t_{rr}	Body Diode Reverse Recovery Time	I_F=-10A, dI/dt=100A/μs		35	55	ns
Q_{rr}	Body Diode Reverse Recovery Charge	I_F=-10A, dI/dt=100A/μs		30	45	nC

A. The value of $R_{\theta JA}$ is measured with the device mounted on 1in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A =25° C. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150° C. The value in any given application depends on the user's specific board design, and the maximum temperature of 150° C may be used if the PCB allows it.
B. The power dissipation P_D is based on $T_{J(MAX)}$=150° C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150° C. Ratings are based on low frequency and duty cycles to keep initial T_J=25° C.
D. The $R_{\theta JA}$ is the sum of the thermal impedence from junction to case $R_{\theta JC}$ and case to ambient.
E. The static characteristics in Figures 1 to 6 are obtained using <300μs pulses, duty cycle 0.5% max.
F. These curves are based on the junction-to-case thermal impedence which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}$=150° C. The SOA curve provides a single pulse rating.
G. The maximum current rating is package limited.
H. These tests are performed with the device mounted on 1 in^2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25° C.

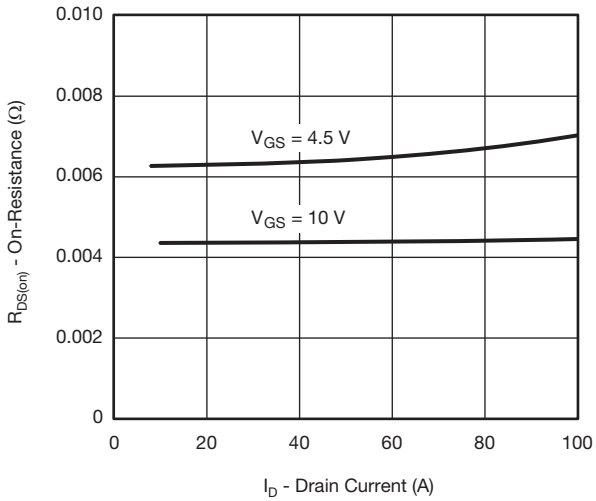
AL ELECTRICAL AND THERMAL CHARACTERISTICS



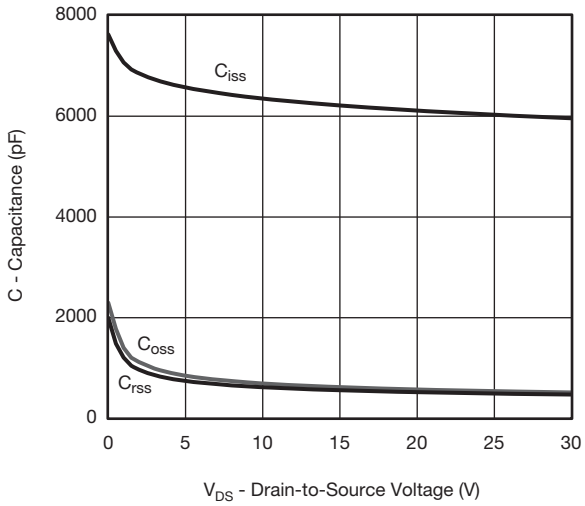
Output Characteristics



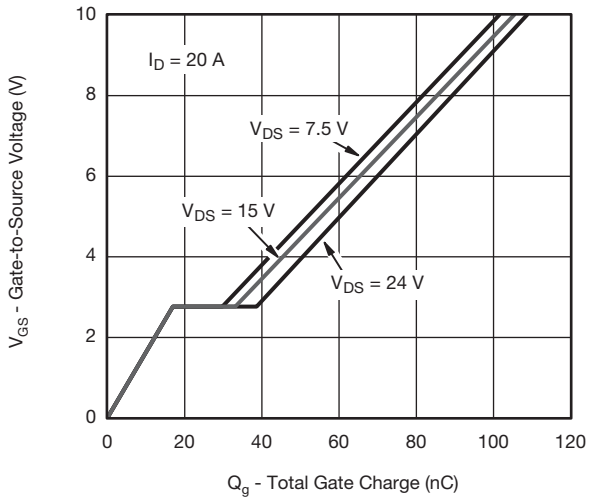
Transfer Characteristics



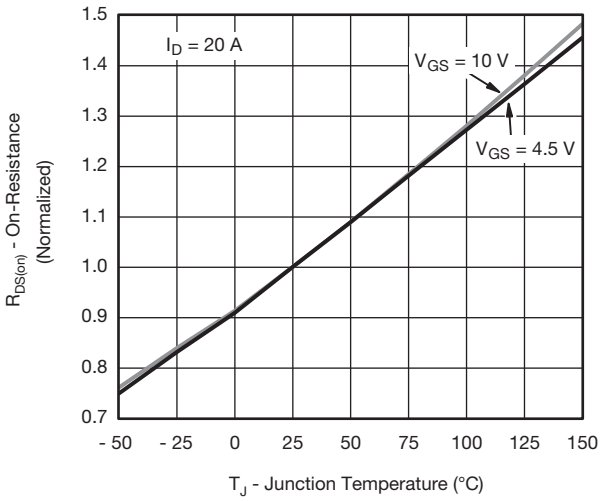
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

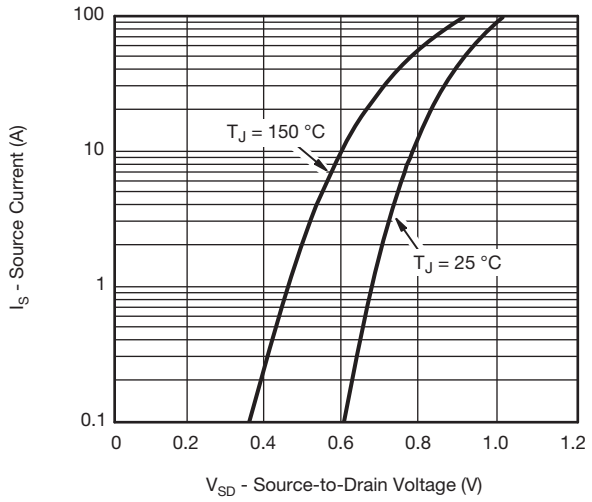


Gate Charge

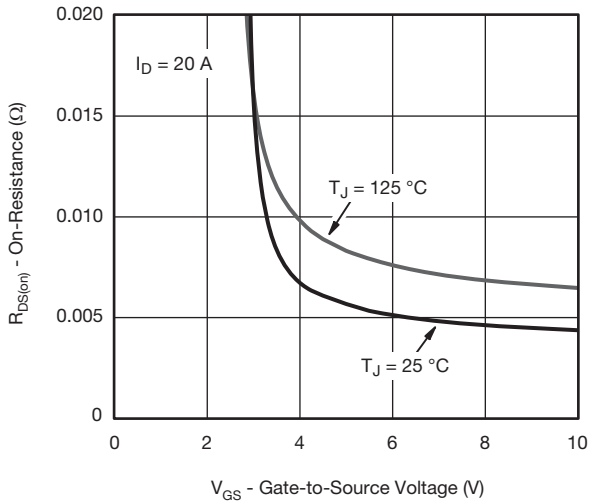


On-Resistance vs. Junction Temperature

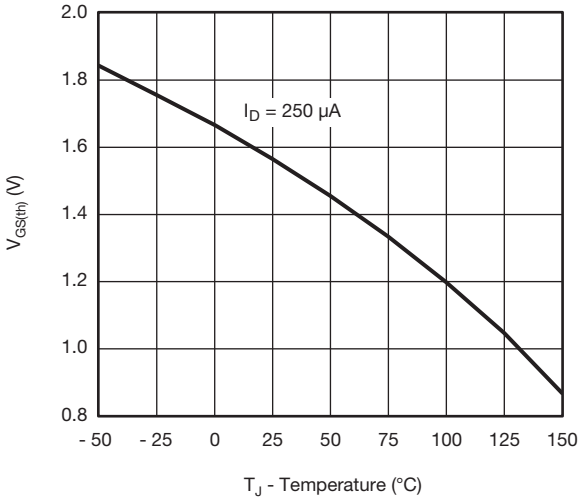
TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



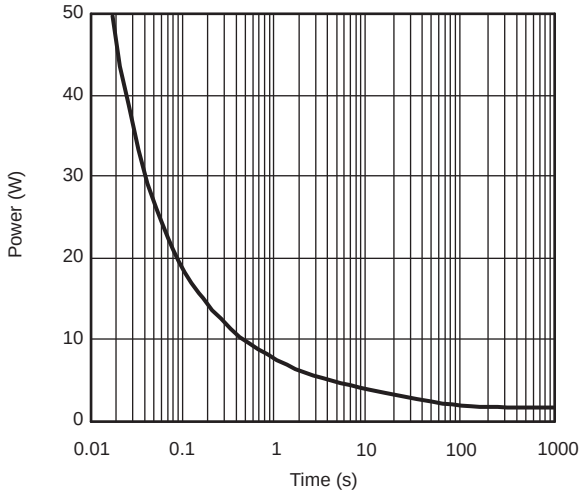
Source-Drain Diode Forward Voltage



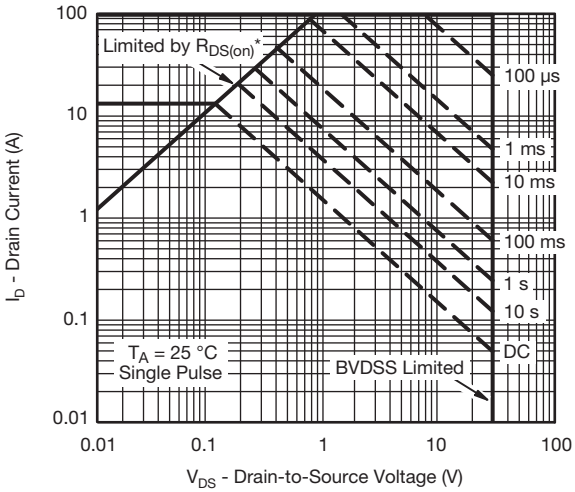
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



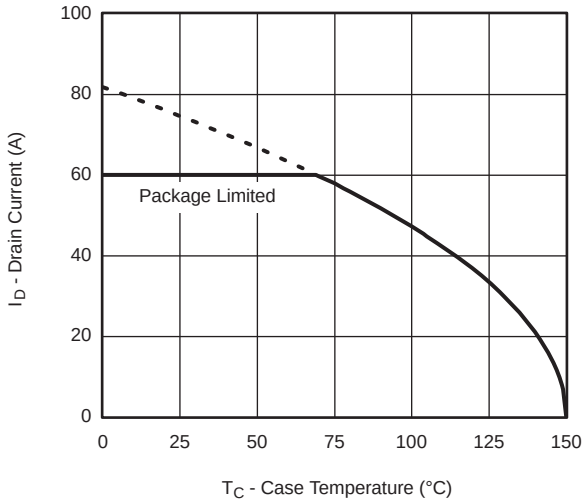
Single Pulse Power



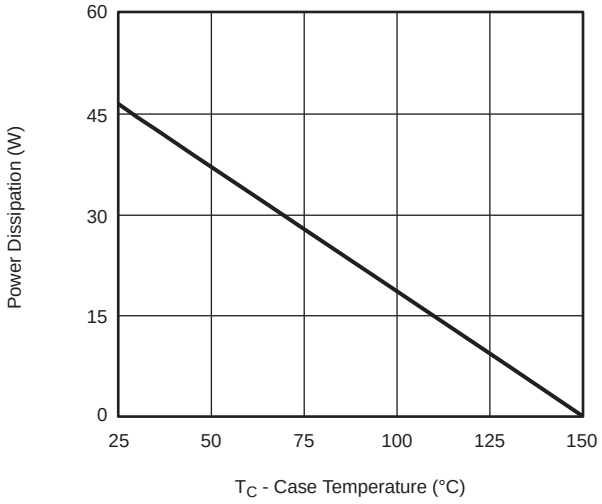
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



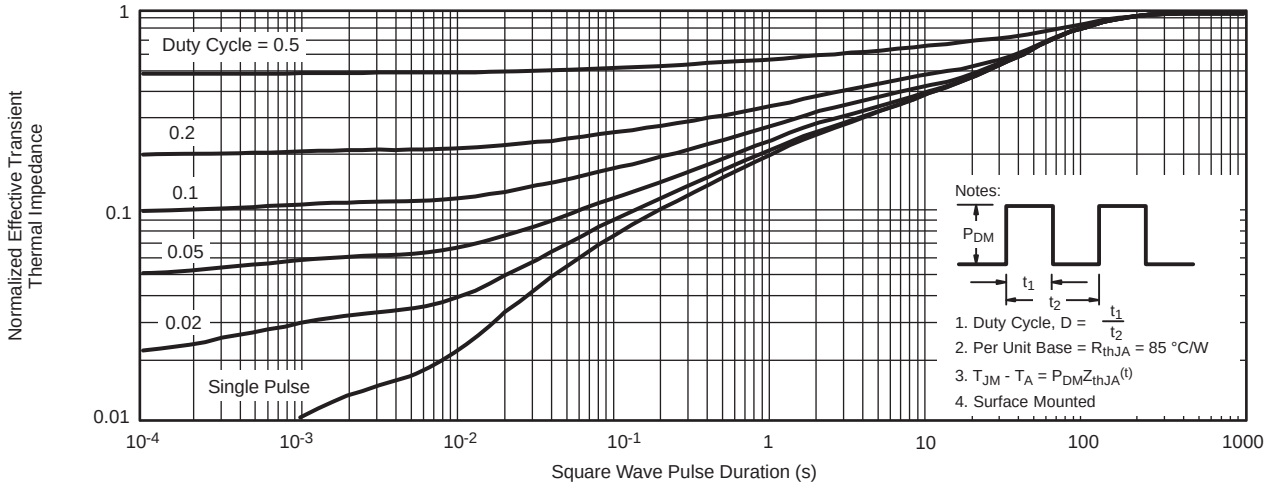
Current Derating*



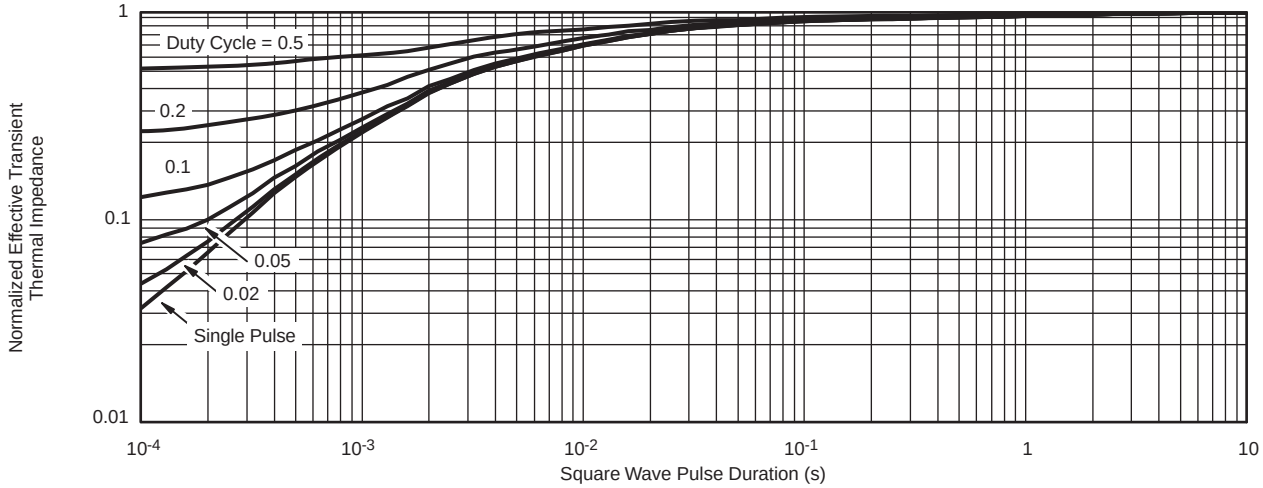
Power, Junction-to-Case

* The power dissipation P_D is based on $T_{J(max)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

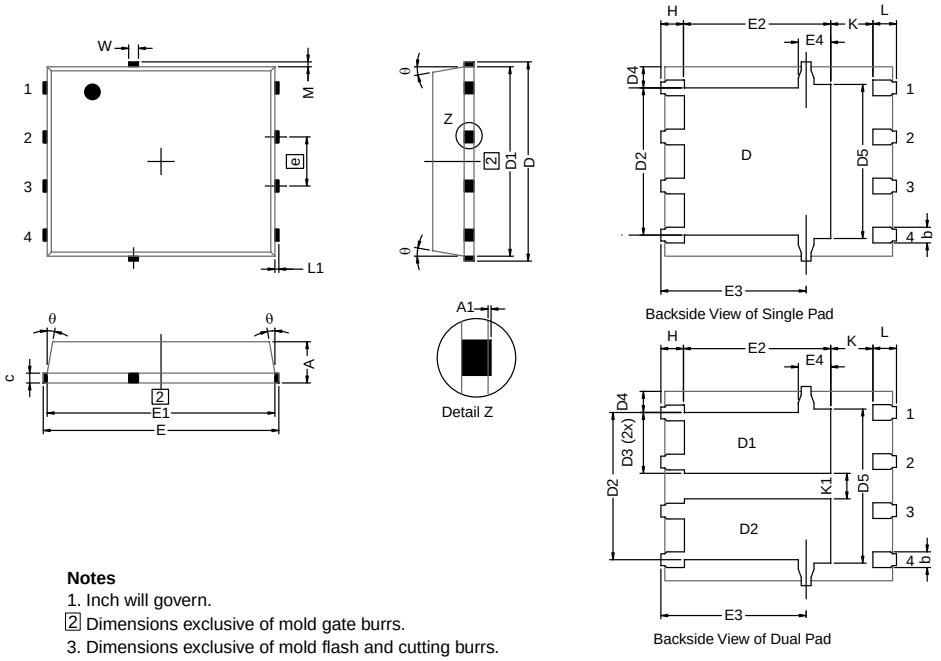


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Power5x6 (Single/Dual) Package Information



Notes
1. Inch will govern.
2. Dimensions exclusive of mold gate burrs.
3. Dimensions exclusive of mold flash and cutting burrs.

DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.97	1.04	1.12	0.038	0.041	0.044
A1		-	0.05	0	-	0.002
b	0.33	0.41	0.51	0.013	0.016	0.020
c	0.23	0.28	0.33	0.009	0.011	0.013
D	5.05	5.15	5.26	0.199	0.203	0.207
D1	4.80	4.90	5.00	0.189	0.193	0.197
D2	3.56	3.76	3.91	0.140	0.148	0.154
D3	1.32	1.50	1.68	0.052	0.059	0.066
D4	0.57 typ.			0.0225 typ.		
D5	3.98 typ.			0.157 typ.		
E	6.05	6.15	6.25	0.238	0.242	0.246
E1	5.79	5.89	5.99	0.228	0.232	0.236
E2 (for AL product)	3.30	3.48	3.66	0.130	0.137	0.144
E2 (for other product)	3.48	3.66	3.84	0.137	0.144	0.151
E3	3.68	3.78	3.91	0.145	0.149	0.154
E4 (for AL product)	0.58 typ.			0.023 typ.		
E4 (for other product)	0.75 typ.			0.030 typ.		
e	1.27 BSC			0.050 BSC		
K (for AL product)	1.45 typ.			0.057 typ.		
K (for other product)	1.27 typ.			0.050 typ.		
K1	0.56	-	-	0.022	-	-
H	0.51	0.61	0.71	0.020	0.024	0.028
L	0.51	0.61	0.71	0.020	0.024	0.028
L1	0.06	0.13	0.20	0.002	0.005	0.008
θ	0°	-	12°	0°	-	12°
W	0.15	0.25	0.36	0.006	0.010	0.014
M	0.125 typ.			0.005 typ.		